

3A, 50V - 600V Surface Mount Super Fast Rectifier

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- Low profile package
- Super fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.11 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	3	A
V_{RRM}	50 - 600	V
I_{FSM}	100	A
T_{JMAX}	150	°C
Package	DO-214AA (SMB)	
Configuration	Single die	



DO-214AA (SMB)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)										
PARAMETER	SYMBOL	ES 3AB	ES 3BB	ES 3CB	ES 3DB	ES 3FB	ES 3GB	ES 3HB	ES 3JB	UNIT
Marking code on the device		ES 3AB	ES 3BB	ES 3CB	ES 3DB	ES 3FB	ES 3GB	ES 3HB	ES 3JB	
Repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400	500	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	30	70	105	140	210	280	350	420	V
Forward current	$I_{F(AV)}$	3								A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	100								A
Junction temperature	T_J	- 55 to +150								°C
Storage temperature	T_{STG}	- 55 to +150								°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	24	$^{\circ}C/W$
Junction-to-ambient thermal resistance	$R_{\theta JA}$	84	$^{\circ}C/W$
Junction-to-case thermal resistance	$R_{\theta JC}$	26	$^{\circ}C/W$

Thermal Performance Note: Units mounted on recommended PCB (10mm x 10mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT	
Forward voltage per diode ⁽¹⁾	ES3AB ES3BB ES3CB ES3DB	$I_F = 1.5A, T_J = 25^{\circ}C$	V_F	0.80	0.92	V	
	ES3FB ES3GB			0.90	1.04	V	
	ES3HB ES3JB			1.11	1.30	V	
	ES3AB ES3BB ES3CB ES3DB	$I_F = 3.0A, T_J = 25^{\circ}C$	V_F	0.86	1.00	V	
	ES3FB ES3GB			0.98	1.13	V	
	ES3HB ES3JB			1.24	1.45	V	
	Forward voltage per diode ⁽¹⁾	ES3AB ES3BB ES3CB ES3DB	$I_F = 1.5A, T_J = 125^{\circ}C$	V_F	0.66	0.75	V
		ES3FB ES3GB			0.73	0.85	V
		ES3HB ES3JB			0.85	0.98	V
		ES3AB ES3BB ES3CB ES3DB	$I_F = 3.0A, T_J = 125^{\circ}C$	V_F	0.73	0.84	V
		ES3FB ES3GB			0.83	0.95	V
		ES3HB ES3JB			0.99	1.13	V
Reverse current @ rated V_R per diode ⁽²⁾		$T_J = 25^{\circ}C$	I_R	-	10	μA	
		$T_J = 125^{\circ}C$		-	100	μA	
Junction capacitance	ES3AB ES3BB ES3CB ES3DB	1 MHz, $V_R = 4.0V$	C_J	46	-	pF	
	ES3FB ES3GB			41	-	pF	
	ES3HB ES3JB			34	-	pF	
Reverse recovery time		$I_F = 0.5A, I_R = 1.0A$ $I_{RR} = 0.25A$	t_{rr}	-	35	ns	

Notes:

1. Pulse test with $PW = 0.3$ ms
2. Pulse test with $PW = 30$ ms

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ES3xB (Note 1, 2)	H	R5	G	SMB	850 / 7" Plastic reel
		R4		SMB	3,000 / 13" Paper reel
		M4		SMB	3,000 / 13" Plastic reel

Notes:

1. "x" defines voltage from 50V (ES3AB) to 600V (ES3JB)
2. Whole series with green compound (halogen-free)

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ES3JBHR5G	ES3JB	H	R5	G	AEC-Q101 qualified Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

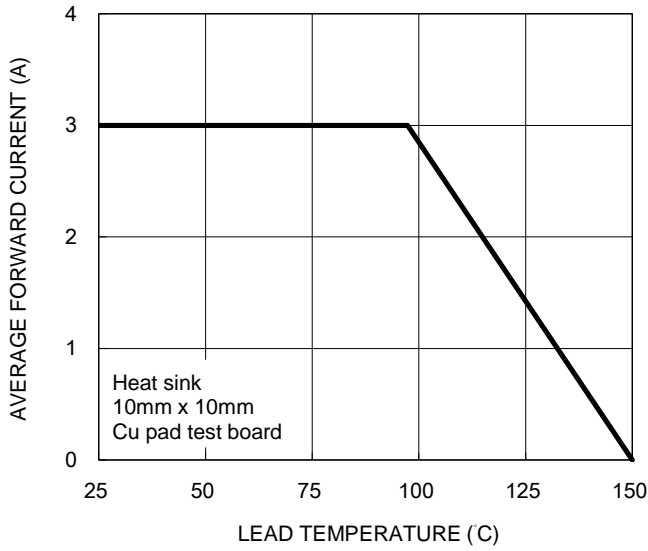


Fig.2 Typical Junction Capacitance

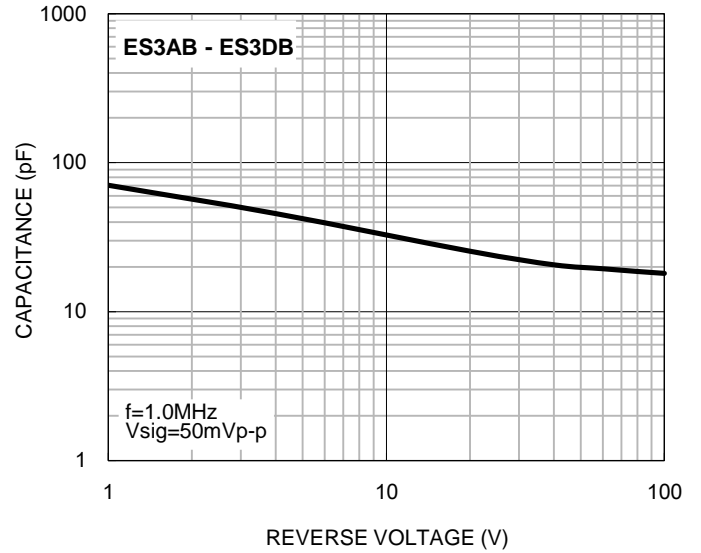


Fig.3 Typical Reverse Characteristics

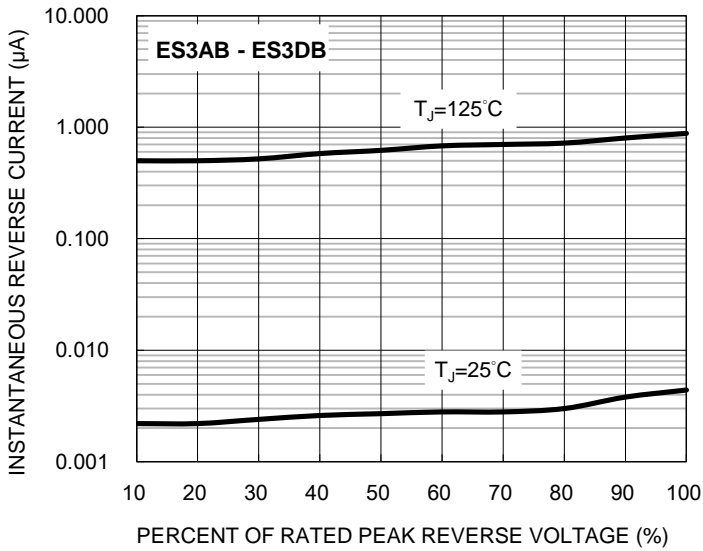
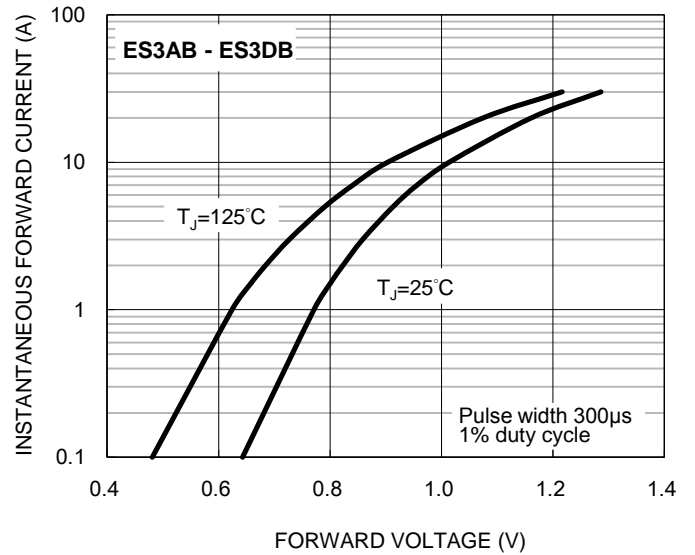


Fig.4 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.5 Typical Junction Capacitance

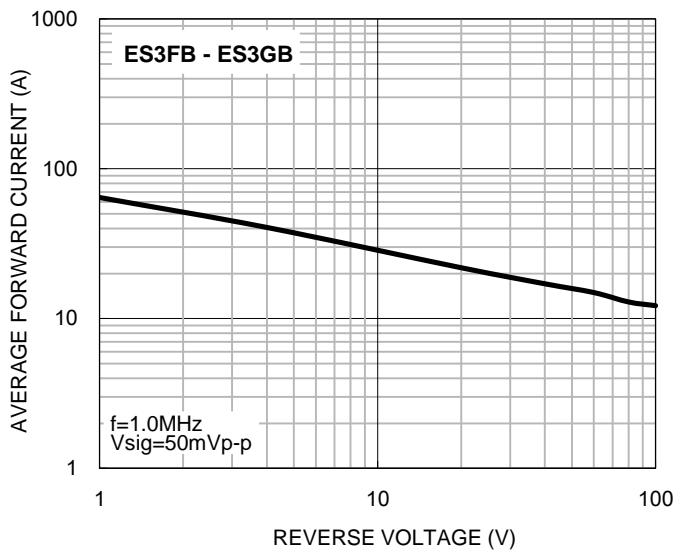


Fig.6 Typical Reverse Characteristics

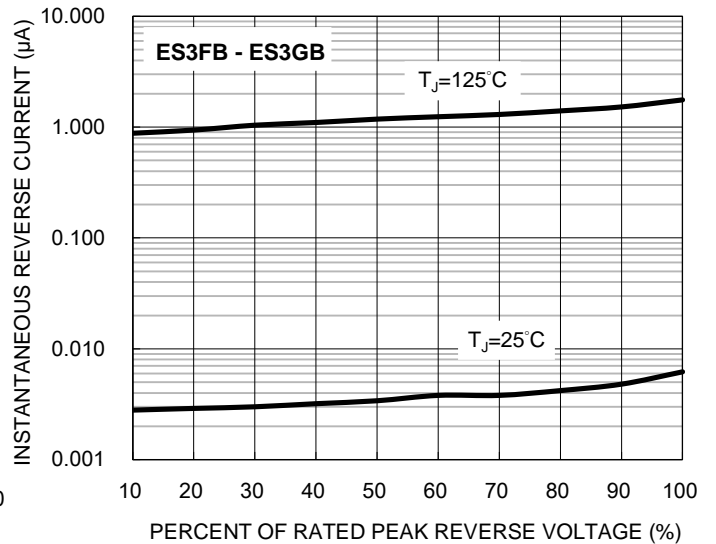
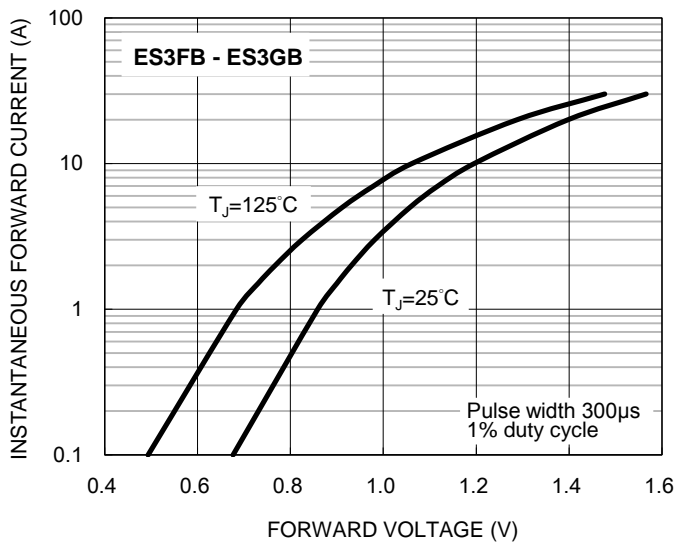


Fig.7 Typical Forward Characteristics



CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.8 Typical Junction Capacitance

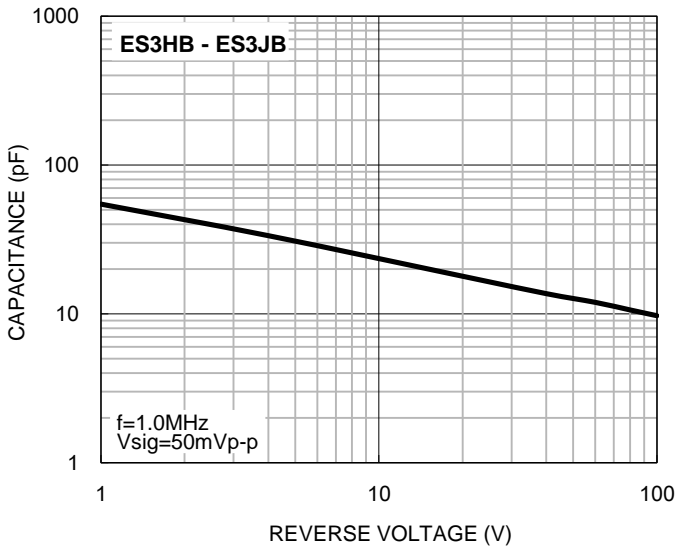


Fig.9 Typical Reverse Characteristics

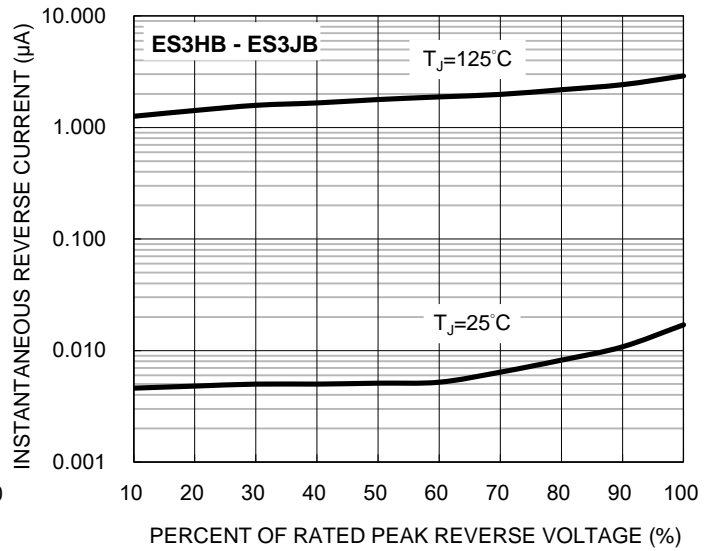
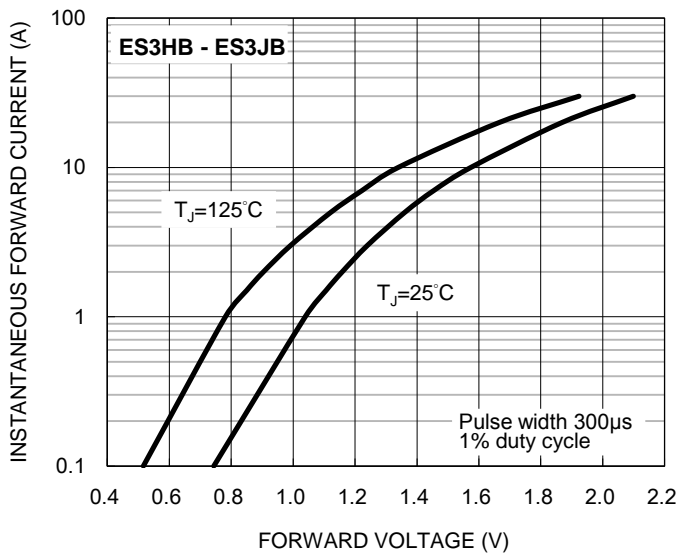
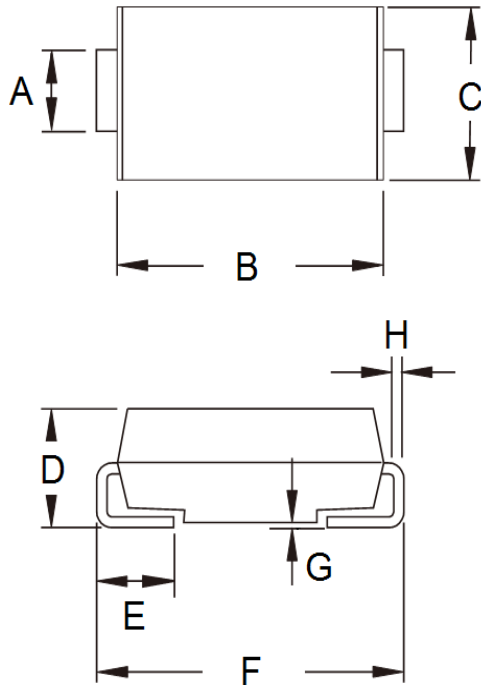


Fig.10 Typical Forward Characteristics



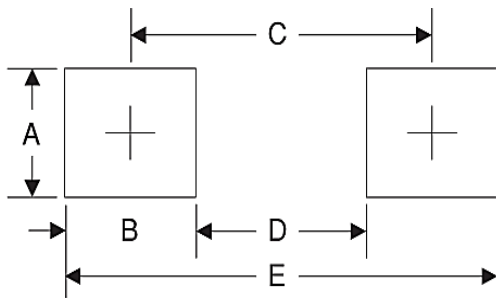
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.95	2.20	0.077	0.087
B	4.05	4.60	0.159	0.181
C	3.30	3.95	0.130	0.156
D	1.95	2.65	0.077	0.104
E	0.75	1.60	0.030	0.063
F	5.10	5.60	0.201	0.220
G	0.05	0.20	0.002	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
B	2.5	0.098
C	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code

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